

**PATENT ASSIGNMENT**

Electronic Version v1.1  
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
MIN SUK SUH	08/30/2007
RECEIVING PARTY DATA	
Name:	HYNIX SEMICONDUCTOR INC.
Street Address:	San 136-1, Ami-ri, Bubal-eub, Icheon-si
City:	Kyongki-do
State/Country:	KOREA, REPUBLIC OF
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	11856149
CORRESPONDENCE DATA	
Fax Number:	(312)427-6663
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	3124271300
Email:	nicholas.kubacki@ladas.net
Correspondent Name:	RICHARD J. STREIT
Address Line 1:	LADAS & PARRY, 224 SOUTH MICHIGAN AVE.
Address Line 4:	CHICAGO, ILLINOIS 60604
ATTORNEY DOCKET NUMBER:	CU-5970 WWP/NK
NAME OF SUBMITTER:	Woochoon W. Park
Total Attachments: 2 source=cu5970assign#page1.tif source=cu5970assign#page2.tif	

CH \$40.00 11856149

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**UNITED STATES OF AMERICA**  
**ASSIGNMENT**

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In consideration of the payment of ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for the other good and valuable consideration,

**ASSIGNOR:**

Name : Min Suk SUH

Address : 112-203, Samsung Apt., Sindang 4-dong, Jung-gu, Seoul, Korea

(INVENTOR NAME AND ADDRESS)

hereby sells, assigns and transfers to

**ASSIGNEE:**

Name : Hynix Semiconductor Inc.

Address : San 136-1, Ami-ri, Bubal-eub, Icheon-si, Kyoungki-do, Korea

(ASSIGNEE NAME AND ADDRESS)

and the successors, assigns and legal representatives of the ASSIGNEE the entire right, title and interest for the United States and its territorial possessions in and to, any and all improvements which are disclosed in the invention entitled:

SEMICONDUCTOR PACKAGE THROUGH-ELECTRODE SUITABLE FOR A STACKED SEMICONDUCTOR PACKAGE AND SEMICONDUCTOR PACKAGE HAVING THE SAME

(TITLE)

and which is found in *(check one applicable item below)*

U.S. patent application executed on even date herewith

U.S. Application Serial No. \_\_\_\_\_ filed on \_\_\_\_\_

and, in and to all Letters Patent to be obtained for said invention by the above application or any continuation, division, renewal, substitute, reissue or re-examination thereof.

ASSIGNOR hereby convenants that no assignment, sale agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale;

ASSIGNOR further convenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference or litigation related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits

required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the purposes thereof.

IN WITNESS WHEREOF, I/we have set our hand and seal

August 30, 2007

\_\_\_\_\_  
Date

*Min Suk Suh*

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INVENTOR: Min Suk SUH

0699P/1

PATENT

RECORDED: 09/17/2007

REEL: 019832 FRAME: 0599